



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D
<i>* : Required Field</i>			

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2015-01-27
Contact Name *	Refer to "Supplier Comment" section	Contact Title	Refer to "Supplier Comment" section
Contact Phone *	Refer to "Supplier Comment" section	Contact Email *	Refer to "Supplier Comment" section
Authorized Representative *	Giovanni Giacopello	Representative Title	AMS & IPD Materials Declaration Champion
Representative Phone *	Refer to "Supplier Comment" section	Representative Email *	Refer to "Supplier Comment" section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement

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Legal Statement

Supplier Acceptance *	true	Legal Declaration *	Standard
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Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	A5L7*UR15AJ6	A	MU1A	2015-01-27
Amount	UoM	Unit type	ST ECOPACK Grade	
1535.70	mg	Each	ECOPACK® 1	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles	 life.augmented	
NAC	NAC	NAC		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy		
Not Applicable ; if coating is used o	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape
DIP	24.38 - 6.35 - 3.3	16	Through-hole
Comment	Package: PDIP 20 .3 CU .4; MDF valid for L6205N		

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
Product(s) meets EU RoHS requirement without any exemptions	false
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	true
Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Product(s) is obsolete, no information is available	false
Product(s) is unknown, no information is available	false
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

QueryList : REACH-16th June 2014				
Query				Response
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	ASL7*UR15AJ6					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die or Dies	Other inorganic materials	14.747	mg	supplier	die	Silicon (Si)	7440-21-3		14.193	mg	962433	9242
Die or Dies				supplier	metallization	Aluminium (Al)	7429-90-5		0.107	mg	7256	70
Die or Dies				supplier	metallization	Titanium (Ti)	7440-32-6		0.012	mg	814	8
Die or Dies				supplier	passivation	Silicon Nitride (SiN)	68034-42-4		0.032	mg	2170	21
Die or Dies				supplier	passivation	Silicon Oxide(SiO2)	7631-86-9		0.185	mg	12545	120
Die or Dies				supplier	back side metallization	Chromium (Cr)	7440-47-3		0.008	mg	542	5
Die or Dies				supplier	back side metallization	Gold (Au)	7440-57-5		0.022	mg	1492	14
Die or Dies				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.072	mg	4882	47
Die or Dies				supplier	polymer die coating	PIX1 Gamma-butyrolactone	96-48-0		0.116	mg	7866	76
Leadframe	Copper & its alloys	710.416	mg	supplier	alloy	Copper (Cu)	7440-50-8		709.168	mg	998243	461788
Leadframe				supplier	alloy	Iron (Fe)	7439-89-6		0.710	mg	999	462
Leadframe				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.213	mg	300	139
Leadframe				supplier	metallization	Silver (Ag)	7440-22-4		0.325	mg	457	212
Soft solder	Solder	9.231	mg	JIG - R	solder	Lead (Pb)	7439-92-1	7a-Lead in high me	9.001	mg	975084	5861
Soft solder				supplier	solder	Silver (Ag)	7440-22-4		0.138	mg	14950	90
Soft solder				supplier	solder	Tin (Sn)	7440-31-5		0.092	mg	9966	60
Bonding wire	Precious metals	2.203		supplier	wire	Gold (Au)	7440-57-5		2.203	mg	1000000	1435
encapsulation	Other inorganic materials	797.503	mg	supplier	mold compound	Epoxy Cresol Novolak	29690-82-2		107.663	mg	135000	70107
encapsulation				supplier	mold compound	Phenol resin	9003-35-4		43.863	mg	55000	28562
encapsulation				supplier	mold compound	Tetrabromobisphenol	79-94-7		19.937	mg	24999	12982
encapsulation				supplier	mold compound	Antimony Trioxide	1309-64-4		2.393	mg	3001	1558
encapsulation				supplier	mold compound	Antimony pentoxide	1314-60-9		9.570	mg	12000	6232
encapsulation				supplier	mold compound	carbon black	1333-86-4		3.988	mg	5001	2597
encapsulation				supplier	mold compound	Mixed siloxanes	Proprietary		11.963	mg	15001	7790
encapsulation				supplier	mold compound	Acrylic resin	9003-01-4		15.950	mg	20000	10386
encapsulation				supplier	mold compound	Silica, vitreous	60676-86-0		574.200	mg	719997	373901
encapsulation				supplier	mold compound	Silica Cristobalite	14464-46-1		3.988	mg	5001	2597
encapsulation				supplier	mold compound	Quartz	14808-60-7		3.988	mg	5001	2597
connections coating	Solder	1.600	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		1.600	mg	1000000	1042